

Date Created : 2008/08/06
Date Issued On : 2008/08/18
PCN# : Q3083203

INFORMATION ONLY NOTIFICATION

The Fine Line wafer process variant of the FS50 200 mm process, whose previous qualification was notified via PCN # Q1080305-A, has been completed. The evaluation of characterization data and reliability data of FAN5355C00X has determined the manufacturing process to be equivalent to the already qualified 150 mm FS50 Fine Line process. The data is available for review upon request.

This is to inform you that a minor change is being made to the following product(s). This notification is for your information only.

If you have any questions concerning this change, please contact:

Technical Contact:

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PCN Originator:

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Implementation of change:

Expected 1st Device Shipment Date: 2008/09/10

Earliest Year/Work Week of Changed Product: 0837

Change Type Description: Wafer Diameter

Description of Change (From): FS50 process technology is qualified on 150 mm and 200 mm wafers. The Fine Line (FL) superstructure on the FS50 process is qualified for 150 mm wafers diameter.

Description of Change (To): Convert the Fine Line (FL) process variant of the FS50 process to 200 mm wafers diameter.

Reason for Change : Increase manufacturing capacity

Product Id Description : The FAN5355UC00X product was used for the characterization and evaluation of the Fine Line FS50 wafer process variant. This data is available for review upon request.

Affected FSIDs :

FAN5355MP00X	FAN5355UC00X	FAN5355UC02X
FAN5645MPX		